

ABSTRACT OF THE INVENTION

A curable underfill encapsulant composition, suitable for use in semiconductor packaging, comprises one or more mono- or polyfunctional maleimide compounds, or one or more mono- or polyfunctional vinyl compounds other than maleimide compounds, or a
5 combination of maleimide and vinyl compounds, with a free radical curing agent, and optionally, one or more fillers.

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